Filenam	e: PMP8408_RevC_	bom.xls				
Date: 12	2/20/2012					
		PMP8408	REV C BOM			
		1 1111 0 100	TRET O BOIN			
COUNT	RefDes	Value	Description	Size	Part Number	MFR
	C35	68pF	Capacitor, Ceramic, 50V, C0G, 10%	603	STD	Std
	C5, C6, C7, C8	330pF	Capacitor, Ceramic, 50V, CoG, 10%	603	STD	Std
	C20, C30			603	STD	Std
		1000pF	Capacitor, Ceramic, 50V, C0G, 10%			
	C4, C9	1000pF	Capacitor, Ceramic, 100V, X7R, 10%	603	STD	Std
	C100	1500pF	Capacitor, Ceramic, 50V, X7R, 10%	603	STD	Std
	C1, C2	0.01uF	Capacitor, Ceramic, 100V, X7R, 10%	603	STD	Std
	C13, C19, C29,					
	C36, C38	0.1uF	Capacitor, Ceramic, 50V, X7R, 10%	603	STD	Std
	C34	0.15uF	Capacitor, Ceramic, 50V, X7R, 10%	603	STD	Std
	C32, C33	0.47uF	Capacitor, Ceramic, 16V, X7R, 10%	603	STD	Std
	C12, C18, C28,					
	C39	1uF	Capacitor, Ceramic, X7R, 16V, 10%	603	STD	Std
	C20	DNP	Capacitor, Ceramic, 50V, C0G, 10%	603	STD	Std
	C24, C40	0.1uF	Capacitor, Ceramic, 100V, X7R, 10%	805	STD	Std
	C37	1uF	Capacitor, Ceramic, 25V, X7R, 10%	805	STD	Std
	C10, C11	3.3uF	Capacitor, Ceramic, 16V, X7R, 10%	805	STD	Std
	C3, C14, C15	1000pF	Capacitor, Ceramic, 2KV, X7R, 10%	1210	STD	Std
2	C22, C23	2.2uF	Capacitor, Ceramic, 100V, X7R, 10%	1210	C3225X7R2A225K	TDK
	C16, C17, C26,					
4	C27	100uF	Capacitor, Ceramic, 6.3V, 20%	1210	C3225X5R0J107M	TDK
1	C25	DNP	Capacitor, Ceramic, 6.3V, 20%	1210	C3225X5R0J107M	TDK
1	C31	22uF	Capacitor, Aluminum, 25V, 20%	5x5.8mm	EEEFK1E220R	Panasonic
1	C21	22uF	Capacitor, Aluminum, 100V, 20%	8x10.2mm	EEEFK2A220P	Panasonic
4	D1, D2, D3, D4		Diode, Schottky, 1A, 100V	SMA	B1100	Diodes, Inc
	Alternate D1, D2,		, , , , , , , , , , , , , , , , , , ,			
	D3, D4		Diode, Schottky, 1A, 100V	SMA	S100	WTE
	D13		Diode, Switching, 100V, 200mA, 400mW,	SOD-123	MMSD4148	On Semi
1	D15		Diode, Dual Schottky, 200-mA, 30-V	SOT23	BAT54S	Zetex
	D16		Diode, SMT TVS 400W, 4.3-A, 58-V	SMA	SMAJ58A	Diodes
	D6, D10		Rectifier, Superfast Power, 200V 1A	SMA	ES1D	Diodes, Inc
	D7	<u> </u>	Diode, Schottky, 1A, 40V	SMA	B140	Diodes, Inc
	D8	10V	Diode, Zener, 10V, 250mW	SOT-23	BZX84C10LT1	On Semi
	D9, D11, D12, D14	101	Diode, Schottky, 0.5A, 30V	SOD-123	MBR0530	On Semi
	FB1, FB2, FB3,	 	2.535, 55nothly, 5.57, 50V	000 120		
	FB4	15	Bead, Ferrite, SMT, 15 Ohms, 1.5A	805	MMZ2012R150A	TDK
	J1, J3	10	Connector, Jack, Modular, 8 POS	0.705 x 0.820	520252	AMP
	J6, J7, J8, J9	 	Terminal Block, 2-pin, 6-A, 3.5mm	0.703 x 0.820 0.27 x 0.25	ED555/2DS	OST
		DNP				~ ~ .
U	L1	DINP	Inductor, SMT, 0.79A, 300milliohm	3.5x3.7mm	VLF4012AT-100MR79	9 TDK

4	Q1, Q2, Q3, Q4		Transistor, NFET, 100V, 1.5A, 250 milliohm	SOT-23	Si2328DS	Vishay
	Alternate, Q1, Q2,					
0	Q3, Q4		Transistor, NFET, 100V, 1.7A, 240 milliohm	SOT-23	AP2330GN-HF	APEC
2	Q6, Q9		Transistor, MOSFET, N-Chan, 30V, 65A, 11.8milliOhm	QFN-8 Power	CSD17507Q5A	TI
2	Q7, Q10		Transistor, PNP, 40V, 200mA, 225mW	SOT23	MMBT3906LT1G	On Semi
1	Q8		Trans, Nch, 150V, 2.3A, 144milliohm	SuperSOT-6	FDC86244	Fairchild
2	R16, R30	0	Resistor, Chip, 1/16W, 5%	603	STD	Std
3	R20, R21, R25	10	Resistor, Chip, 1/16W, 5%	603	STD	Std
1	R17	49.9	Resistor, Chip, 1/16W, 1%	603	STD	Std
2	R3, R4	75	Resistor, Chip, 1/16W, 1%	603	STD	Std
1	R44	90.9	Resistor, Chip, 1/16W, 1%	603	STD	Std
1	R37	237	Resistor, Chip, 1/16W, 1%	603	STD	Std
1	R40	402	Resistor, Chip, 1/16W, 1%	603	STD	Std
1	R22	825	Resistor, Chip, 1/16W, 1%	603	STD	Std
1	R41	1K	Resistor, Chip, 1/16W, 1%	603	STD	Std
1	R38	2K	Resistor, Chip, 1/16W, 1%	603	STD	Std
1	R50	3.01K	Resistor, Chip, 1/16W, 1%	603	STD	Std
3	R31, R34, R39	10K	Resistor, Chip, 1/16W, 1%	603	STD	Std
1	R42	68.1K	Resistor, Chip, 1/16W, 1%	603	STD	Std
1	R43	24.9K	Resistor, Chip, 1/16W, 1%	603	STD	Std
1	R47	5.90K	Resistor, Chip, 1/16W, 1%	603	STD	Std
1	R48	20K	Resistor, Chip, 1/16W, 1%	603	STD	Std
1	R46	69.8K	Resistor, Chip, 1/16W, 1%	603	STD	Std
1	R49	100K	Resistor, Chip, 1/16W, 1%	603	STD	Std
	R11, R12, R13,					
4	R14	150K	Resistor, Chip, 1/16W, 1%	603	STD	Std
4	R7, R8, R9, R10	499K	Resistor, Chip, 1/16W, 1%	603	STD	Std
	R23, R24	1	Resistor, Chip, 1/10W, 1%	805	STD	Std
2	R19, R26	10	Resistor, Chip, 1/10W, 5%	805	STD	Std
1	R27	20	Resistor, Chip, 1/10W, 5%	805	STD	Std
1	R18	39K	Resistor, Chip, 1/10W, 5%	805	STD	Std
1	T1		XFMR, 1000 Base-T, Ratio 1:1	0.500 x 0.370 inch	H2019	Pulse
1	T2		Transformer, Flyback	13.5x17.75 mm	NA6069-AL	Coilcraft
0	Alternate T2		Transformer, Flyback	13.5x17.75 mm	LDT0571-50	LinkCom
1	T3		Transformer, Gate Drive, 1mH	9.7x7.8mm	LTC0266-50	LinkCom
1	U5		IC, Photocoupler, 80-160% CTR	SOP-4	LTV817AS	Lite-on
1	U6		IC, Precision Adjustable Shunt Regulator, 1%	SOT23-5	TLV431ACDBVR	TI
1	U4		IC, High Power/Efficiency PoE PD and DC/DC Controller	HTSSOP-24	TPS23785BPWP	TI

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